## 505675511 09/17/2019

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
MICHAEL W. CUMBIE	04/18/2017
VIKTOR SHKOLNIKOV	04/18/2017
CHIEN-HUA CHEN	04/18/2017

#### **RECEIVING PARTY DATA**

Name:	Hewlett-Packard Development Company, L.P.	
Street Address:	10300 Energy Drive	
City:	Spring	
State/Country:	TEXAS	
Postal Code:	77389	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16494856

#### **CORRESPONDENCE DATA**

**Fax Number:** (970)778-4063

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided: if that is unsuccessful, it will be sent via US Mail.

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** (541)360-4450 **Email:** ipa.mail@hp.com

Correspondent Name: HP INC.

Address Line 1: 3390 E. HARMONY ROAD MS 35
Address Line 4: FORT COLLINS, COLORADO 80528

ATTORNEY DOCKET NUMBER:	85802048
NAME OF SUBMITTER:	GARY P. OAKESON
SIGNATURE:	/Gary P. Oakeson/
DATE SIGNED:	09/17/2019

## **Total Attachments: 4**

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> PATENT REEL: 050399 FRAME: 0176

HP Inc.	
3390 E. Harmony Road	
Mail Stop 35	
Fort Collins, Colorado 808	328

Rev 8/2014 (Assignment)

PATENT APPLICATION

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RECORD ID:	84601713	
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**ASSIGNMENT OF PATENT APPLICATION** I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged. and in furtherance of my/our obligations to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPDC), and to its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPDC, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled: CHIP TO CHIP FLUIDIC INTERCONNECT Filing Date: Application No.: and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-L-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent of any countries thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Patent I/we additionally authorize HPDC to file applications in my/our name for Patent in any country, to be held and enjoyed by HPDC, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made; AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the little to said invention(s) or improvement(s), said application and said Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful caths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation. and assistance are paid by HPDC; AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Patent for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment. I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the Record ID and title set forth above, as soon as the same shall have been made known to them. IN WITNESS WHEREOF, I/we hereuntg set my/our hand(s) and seal(s): Inventor's Signature Michael W Cumbie First/Middle Name Last Name Inventor's Signature Date Viktor Shkolnikov First/Middle Name Last Name

Page 1 of 2

PATENT REEL: 050399 FRAME: 0177 HP Inc. 3390 E. Harmony Road Mail Stop 35 Fort Collins, Colorado 80528

## PATENT APPLICATION

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Chien-Hua	Chen			
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PATENT REEL: 050399 FRAME: 0178

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

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## PATENT APPLICATION

RECORD ID:	<u>84601713</u>

## **ASSIGNMENT OF PATENT APPLICATION**

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to HEWLETT-PACKARD DEVELOPMENT COMPANY L.P. a Texas

Limited Partnership hav subsidiaries and affiliates	ing its principal place of s, agree to assign and tran	f business in Houston, Texas nsfer and hereby assign and trai	(HENT COMPANY, L.P., a Texas , (hereinafter HPDC), and to its nsfer to HPDC, its successors and ad under an application for Patent
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Filing Date:		Application No.:	
divisionals, and renewals	of and substitutes for said	d application for said Patent, ar	tions, continuations-in-part (C-I-P's), and any and all other Patent of any examinations, or extensions of said
by HPDC, its successors, Patent respectively may b	assigns, nominees or lega	al representatives, to the full end ended, as fully and entirely as the	any country, to be held and enjoyed of the term or terms for which said ne same would have been held and
executed and will not executime a request is made, ar perfect the title to said invenominees or legal represe said invention(s) or improve papers, to execute all disrightful oaths and declaratilegal representatives to old	cute any agreement in confut without undue delay, execution(s) or improvement(s) ntatives, and I/we agree to rement(s), said application is claimers and divisionals, cons, and generally to do evotain and enforce, for its or all countries provided the execution is an and service of the execution and enforce.	lict herewith, and I/we further coverute and deliver all such papers and application and said Patern communicate to HPDC, or to its and said Patent, to testify in any continuations, C-I-P's, reissue are erything possible to aid HPDC, its or their own benefit, proper patern	rein assigned, and that I/we have not renant and agree that I/we will, each as may be necessary or desirable to it, to HPDC, its successors, assigns, nominee, all known facts respecting legal proceedings, to sign all lawfulnd foreign applications, to make all successors, assigns, nominees and it protection for said invention(s) or me/us in lending such cooperation
applications as aforesaid,	to issue to HPDC, as assigent(s) which may be issue	gnee of the entire right, title and	whose duty it is to issue patents on interest, any and all Patent for said sult of the application aforesaid, in
I/we further authorize application for Patent, now known to them.	and direct the attorneys identified by the Record ID	of record to insert the filing day	ate and application number of said n as the same shall have been made
IN WITNESS WHERE	OF, I/we hereunto set my	/our hand(s) and seal(s):	
Inventor's Signature	***************************************	Date	
Michael W	Cumbie		
First/Middle Name	Last Name		
TShkohm	· ·	4/18/	117
Inventor's Signature		Date *	
Viktor	Shkolnikov		
First/Middle Name	Last Name		

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**REEL: 050399 FRAME: 0179** 

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

## PATENT APPLICATION

Fort Collins, Colorado 80528		RECORD ID:	84601713
	ASSIGNMENT OF PA	ATENT APPLICATION (cont.	)
Inventor's Signature		Date	
Chien-Hua	Chen		
First/Middle Name	Last Name		
Inventor's Signature		Date	
First/Middle Name	Last Name		
Inventor's Signature		Date	
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Inventor's Signature		Date	
		540	
First/Middle Name	Last Name		

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**RECORDED: 09/17/2019** 

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